

SECOND ANNOUNCEMENT AND CALL FOR PAPERS

2019 SYMPOSIUM ON VLSI TECHNOLOGY

Pushing the Limits of Semiconductors for United and Connected World

RIHGA Royal Hotel Kyoto, Japan

Sunday – Friday, June 9-14, 2019

June 9 Sunday Workshop

June 10 Short Course

June 11-13 Technical Sessions

June 14 Friday Forum

Paper Submission Deadline: 23:59 JST Monday, January 28, 2019

For details, please visit: www.vlssymposium.org

Symposium Scope Papers will be selected based on technical innovation, advances relative to previously published work, credibility of claims, and quality of writing and illustrations. The scope includes:

- **IoT** including ultra-low power, energy harvest, wearable, sensors, display, and communication devices
- **AI** including CPU, GPU, in-memory computing, and stochastic computing
- **Stand-alone and embedded memories** including SRAM, DRAM, 3D NAND, MRAM, PCRAM, ReRAM, FeRAM and other new memories
- **CMOS technology, microprocessors and SoCs** including scaling, manufacturing, and yield optimization
- **RF/analog and sensors** including mixed-signal, analog, I/O, power device, III-Nitride and 2D materials, imaging and MEMS
- **Process and material technologies** including transistor process, high mobility channels, SOI, lithography and patterning, and 3D NAND processes
- **Packaging technologies and system-in-package (SiP)** including TSVs; 3D and 2.5D integration
- **Photonics technology and beyond CMOS devices** including Si photonics; quantum computing and spintronics devices

Focus Sessions will be offered in these areas of interest:

- **Technology & system for AI (Joint with Circuits)**
- **The future of memory (Joint with Circuits)**
- **Quantum computing (Technology)**
- **3D integration and package (Technology)**

Short Courses A full day Short Courses will offer in-depth lectures on some of the topics of highest interest to the VLSI community given by distinguished experts

- **New computing: From security to AI and everything in between (Joint with Circuits)**
- **CMOS technology enablers for pushing the limit of semiconductor: Materials to packaging (Technology)**

Demo Session for Outstanding Papers A demo session will be held during the Joint Circuits/Technology Reception on Monday. At the demo session the authors of the selected papers will showcase some of the most exciting recent innovations in the field.

Friday Forum will give broad perspectives on how semiconductors are shaping the future of Transportation and Autonomous Driving.

Paper Submission Prospective authors must submit two-page camera-ready papers and abstracts through the Symposia's website, www.vlssymposium.org. Accepted papers will be published as submitted, with **no revisions permitted**. Authors must follow detailed instructions provided within the "Authors" section of the website, including the Authors' Guide and Pre-publication Policy.

Best Student Paper Award The selection will be based on quality and presentation of the paper at the Symposium. The winning student will be presented a monetary award and a certificate at the 2020 Symposium opening session. **The student must be enrolled as a full-time student at the time of submission, be the leading author and presenter of the paper**, and indicate when submitting the paper that the paper should be considered for the award.

Call for Workshops The Symposium will host several short 2-hour workshops on Sunday, June 9th. The call for proposals for those Workshops is now open. You organize the workshop, VLSI provides the venue! Check the details in www.vlssymposium.org/satellite-workshops-events/

Secretariat for VLSI Symposia

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